

High Temperature Silicon Carbide Power Schottky Diode

V_{RRM}	=	1200 V
V_F	=	1.7 V
I_F	=	0.75 A
Q_C	=	11 nC

Features

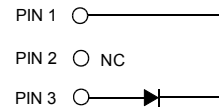
- 1200 V Schottky rectifier
- 250 °C maximum operating temperature
- Electrically isolated base-plate
- Zero reverse recovery charge
- Superior surge current capability
- Positive temperature coefficient of V_F
- Temperature independent switching behavior
- Lowest figure of merit Q_C/I_F
- Available screened to Mil-PRF-19500

Advantages

- High temperature operation
- Improved circuit efficiency (Lower overall cost)
- Low switching losses
- Ease of paralleling devices without thermal runaway
- Smaller heat sink requirements
- Industry's lowest reverse recovery charge
- Industry's lowest device capacitance
- Ideal for output switching of power supplies
- Best in class reverse leakage current at operating temperature

Package

- RoHS Compliant



TO – 257 (Isolated Base-plate Hermetic Package)

Applications

- Down Hole Oil Drilling, Geothermal Instrumentation
- High Temperature DC/DC Converters
- High Temperature Motor and Servo Drives
- High Temperature Inverters
- High Temperature Actuator Control
- Military Power Supplies

Maximum Ratings at $T_j = 250\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	V_{RRM}		1200	V
Continuous forward current	I_F	$T_C \leq 225\text{ °C}$	0.75	A
RMS forward current	$I_{F(RMS)}$	$T_C \leq 225\text{ °C}$	1.3	A
Surge non-repetitive forward current, Half Sine Wave	$I_{F,SM}$	$T_C = 25\text{ °C}$, $t_p = 10\text{ ms}$	8	A
Non-repetitive peak forward current	$I_{F,max}$	$T_C = 25\text{ °C}$, $t_p = 10\text{ }\mu\text{s}$	tbd	A
i^2t value	$\int i^2 dt$	$T_C = 25\text{ °C}$, $t_p = 10\text{ ms}$	tbd	A^2S
Power dissipation	P_{tot}	$T_C = 25\text{ °C}$	24	W
Operating and storage temperature	T_j, T_{stg}		-55 to 250	°C

Electrical Characteristics at $T_j = 250\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Diode forward voltage	V_F	$I_F = 0.75\text{ A}$, $T_j = 25\text{ °C}$		1.74		V
		$I_F = 0.75\text{ A}$, $T_j = 210\text{ °C}$		2.8		
Reverse current	I_R	$V_R = 1200\text{ V}$, $T_j = 25\text{ °C}$		0.1	10	μA
		$V_R = 1200\text{ V}$, $T_j = 275\text{ °C}$		6.6	30	
Total capacitive charge	Q_C	$I_F \leq I_{F,MAX}$ $dI_F/dt = 200\text{ A}/\mu\text{s}$ $T_j = 210\text{ °C}$	$V_R = 400\text{ V}$	6		nC
			$V_R = 960\text{ V}$	11		
Switching time	t_s		$V_R = 400\text{ V}$ $V_R = 960\text{ V}$	< 17		ns
Total capacitance	C	$V_R = 1\text{ V}$, $f = 1\text{ MHz}$, $T_j = 25\text{ °C}$		66		pF
		$V_R = 400\text{ V}$, $f = 1\text{ MHz}$, $T_j = 25\text{ °C}$		10		
		$V_R = 1000\text{ V}$, $f = 1\text{ MHz}$, $T_j = 25\text{ °C}$		8		

Thermal Characteristics

Thermal resistance, junction - case	R_{thJC}	9.52	°C/W
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Mechanical Properties

Mounting torque	M	0.6	Nm
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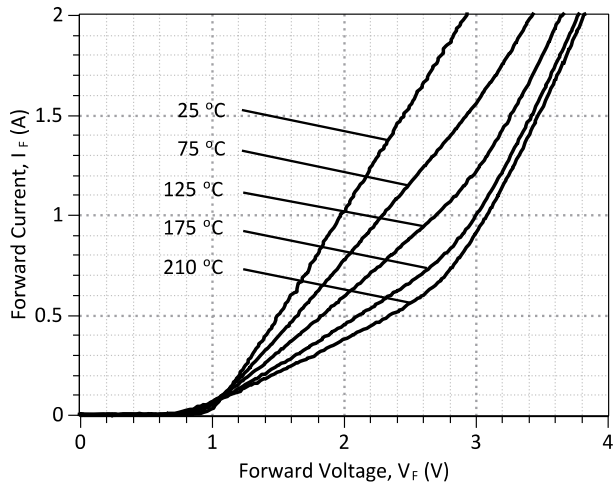


Figure 1: Typical Forward Characteristics

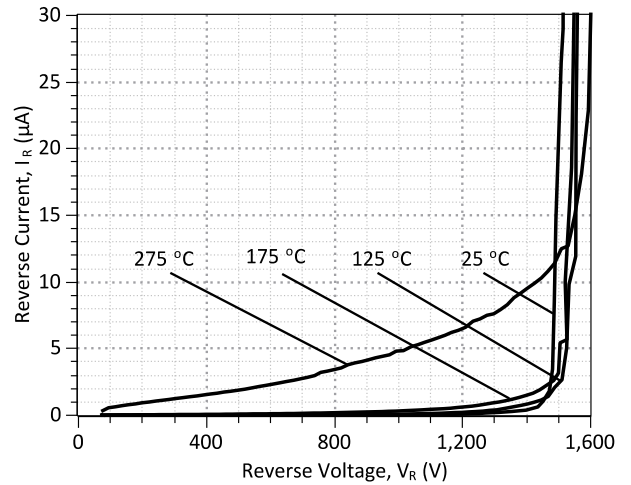


Figure 2: Typical Reverse Characteristics

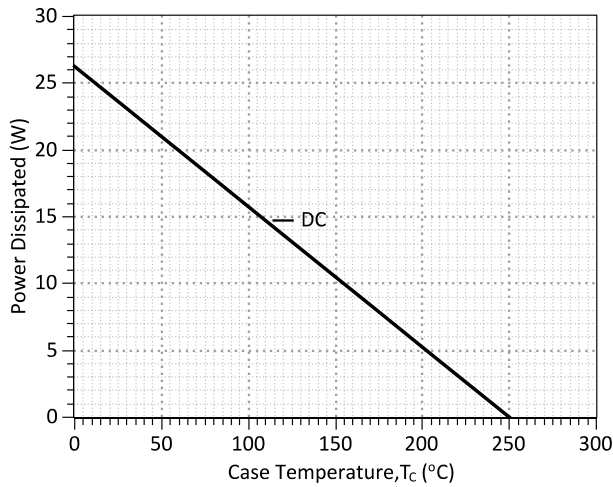
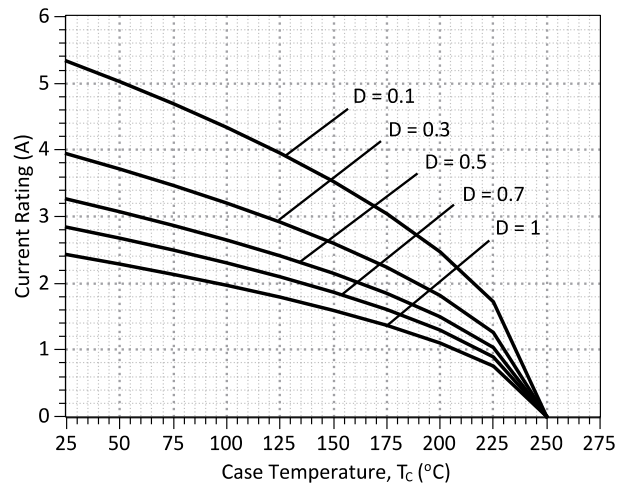


Figure 3: Power Derating Curve



**Figure 4: Current Derating Curves ($D = t_p/T$, $t_p = 400 \mu s$)
(Considering worst case Z_{th} conditions)**

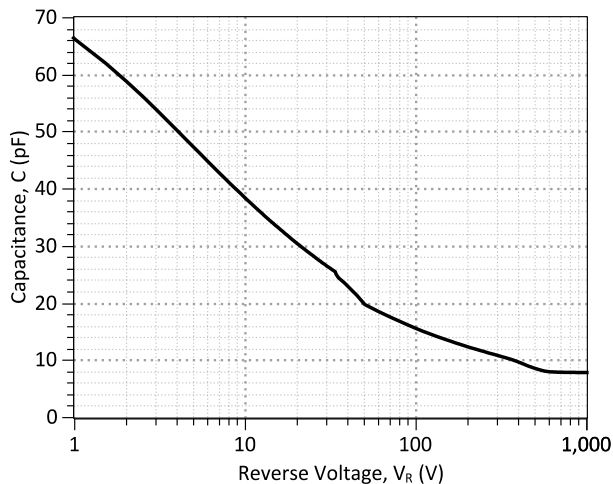


Figure 5: Typical Junction Capacitance vs Reverse Voltage Characteristics

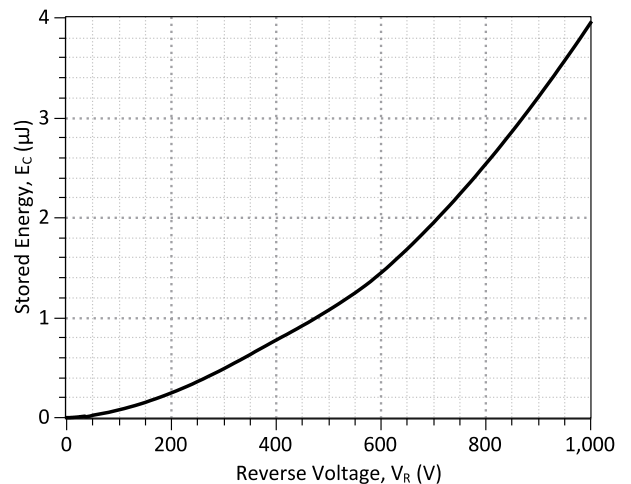


Figure 6: Typical Switching Energy vs Reverse Voltage Characteristics

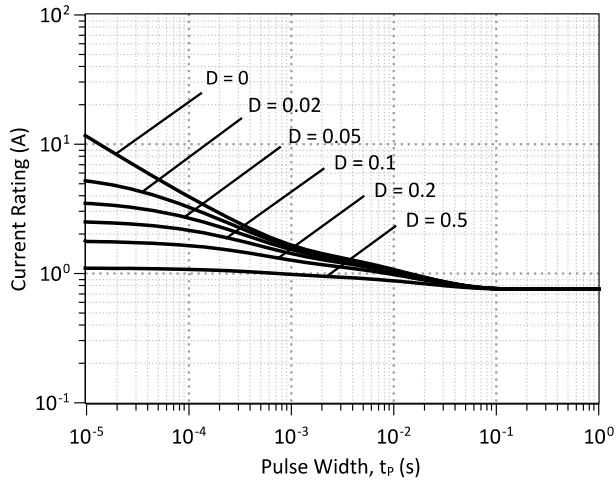


Figure 7: Current vs Pulse Duration Curves at $T_c = 225\text{ }^\circ\text{C}$

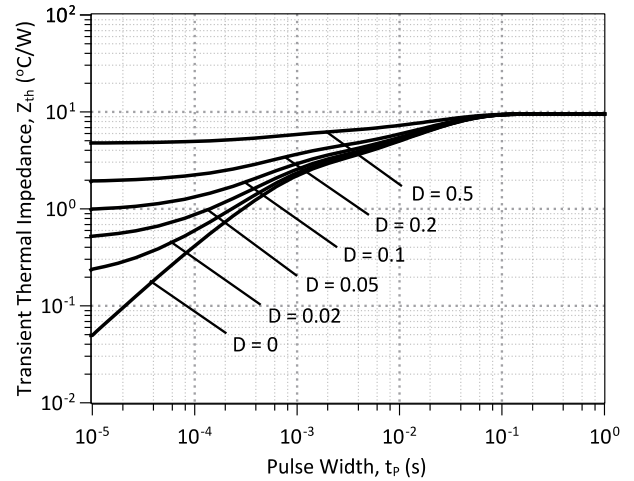
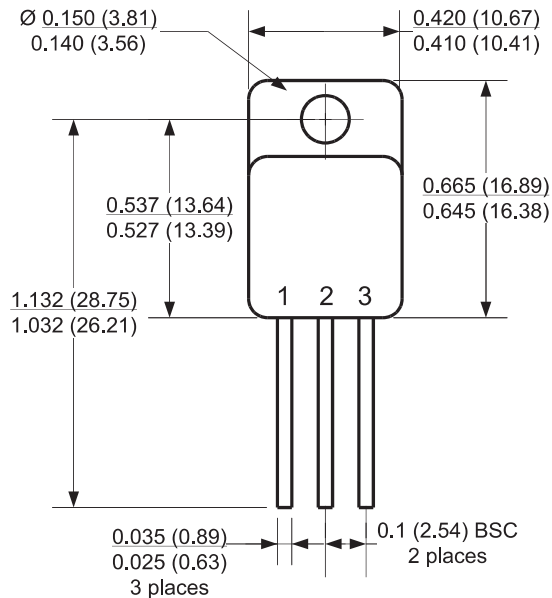


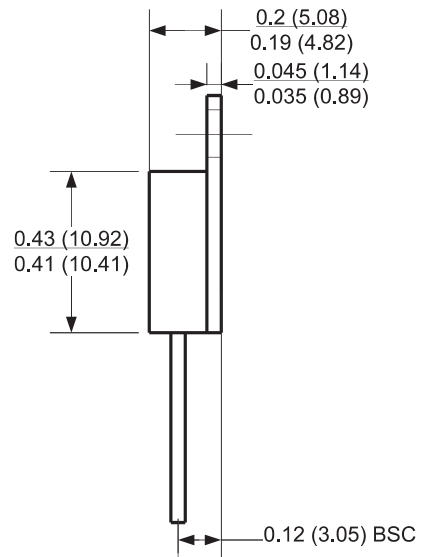
Figure 8: Transient Thermal Impedance

Package Dimensions:

TO-257



PACKAGE OUTLINE



NOTE

1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

Revision History

Date	Revision	Comments	Supersedes
2012/04/24	0	Initial release	

Published by

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SPICE Model Parameters

Copy the following code into a SPICE software program for simulation of the 1N8024-GA device.

```
*      MODEL OF GeneSiC Semiconductor Inc.
*
*      $Revision:   1.0           $
*      $Date:      05-SEP-2013   $
*
*      GeneSiC Semiconductor Inc.
*      43670 Trade Center Place Ste. 155
*      Dulles, VA 20166
*      http://www.genesicsemi.com/index.php/sic-products/schottky
*
*      COPYRIGHT (C) 2013 GeneSiC Semiconductor Inc.
*      ALL RIGHTS RESERVED
*
*      These models are provided "AS IS, WHERE IS, AND WITH NO WARRANTY
*      OF ANY KIND EITHER EXPRESSED OR IMPLIED, INCLUDING BUT NOT LIMITED
*      TO ANY IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A
*      PARTICULAR PURPOSE."
*      Models accurate up to 2 times rated drain current.
*
*      Start of 1N8024-GA SPICE Model
*
.SUBCKT 1N8024 ANODE KATHODE
R1 ANODE INT R=((TEMP-24)*0.0099); Temperature Dependant Resistor
D1 INT KATHODE 1N8024_25C; Call the 25C Diode Model
D2 ANODE KATHODE 1N8024_PIN; Call the PiN Diode Model
.MODEL 1N8024_25C D
+ IS      1.88E-18      RS      0.9255
+ N       1            IKF     98.29122743
+ EG      1.2          XTI     3
+ CJO     7.90E-11     VJ      0.367
+ M       1.63         FC      0.5
+ TT      1.00E-10     BV      1500
+ IBV     1.00E-03     VPK     1200
+ IAVE    1            TYPE    SiC_Schottky
+ MFG     GeneSiC_Semiconductor
.MODEL 1N8024_PIN D
+ IS      2.76E-16     RS      0.84243
+ N       3.791461     IKF     2.98675
+ EG      3.23         XTI     30
+ FC      0.5          TT      0
+ BV      1500         IBV     1.00E-03
+ VPK     1200         IAVE    1
+ TYPE    SiC_PiN
.ENDS
*
*      End of 1N8024-GA SPICE Model
```